BC808-25LT1, BC808-40LT1

General Purpose Transistors

PNP Silicon

Features

• Pb-Free Packages may be Available

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V _{CEO}	-25	V
Collector - Base Voltage	V _{CBO}	-30	V
Emitter - Base Voltage	V _{EBO}	-5.0	V
Collector Current – Continuous	Ic	-500	mAdc

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

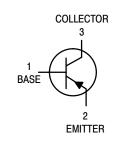
Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board, (Note 1) T _A = 25°C Derate above 25°C	P _D	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T _A = 25°C Derate above 25°C	P _D	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

- 1. $FR-5 = 1.0 \times 0.75 \times 0.062$ in.
- 2. Alumina = $0.4 \times 0.3 \times 0.024$ in 99.5% alumina.



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MARKING DIAGRAM



SOT-23 CASE 318 STYLE 6



x = F = BC808-25LT1= G = BC808-40LT1

D = Date Code

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

BC808-25LT1, BC808-40LT1

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted.)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (I _C = –10 mA)	V _{(BR)CEO}	-25	-	-	V
Collector – Emitter Breakdown Voltage ($V_{EB} = 0$, $I_{C} = -10 \mu A$)	V _{(BR)CES}	-30	-	-	V
Emitter – Base Breakdown Voltage (I _E = –1.0 μA)	V _{(BR)EBO}	-5.0	-	-	V
Collector Cutoff Current $(V_{CB} = -20 \text{ V})$ $(V_{CB} = -20 \text{ V}, T_J = 150^{\circ}\text{C})$	Ісво	- -	_ _	-100 -5.0	nA μA
ON CHARACTERISTICS	•				
DC Current Gain $ (I_{C} = -100 \text{ mA}, V_{CE} = -1.0 \text{ V}) $ BC808–25 BC808–40 $ (I_{C} = -500 \text{ mA}, V_{CE} = -1.0 \text{ V}) $	h _{FE}	160 250 40	- - -	400 600 –	-
Collector – Emitter Saturation Voltage (I _C = –500 mA, I _B = –50 mA)	V _{CE(sat)}	-	_	-0.7	V
Base – Emitter On Voltage (I _C = –500 mA, I _B = –1.0 V)	V _{BE(on)}	-	-	-1.2	V
SMALL-SIGNAL CHARACTERISTICS					
Current – Gain – Bandwidth Product ($I_C = -10 \text{ mA}, V_{CE} = -5.0 \text{ Vdc}, f = 100 \text{ MHz}$)	f _T	100	-	-	MHz
Output Capacitance $(V_{CB} = -10 \text{ V}, f = 1.0 \text{ MHz})$	C _{obo}	-	10	-0.7	pF

DEVICE ORDERING INFORMATION

Device	Package	Shipping [†]
BC808-25LT1	SOT-23	3,000 Tape & Reel
BC808-40LT1	SOT-23	3,000 Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

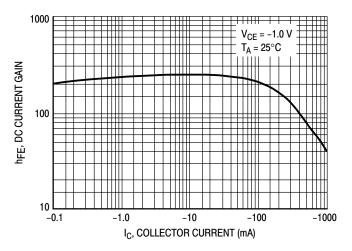


Figure 1. DC Current Gain

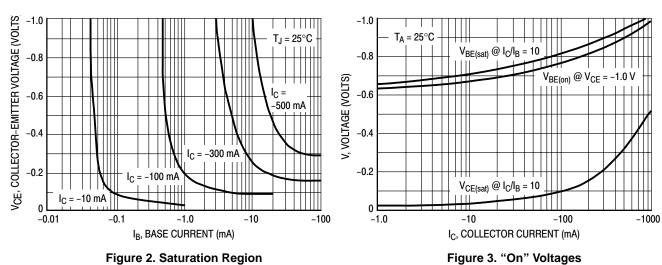


Figure 2. Saturation Region

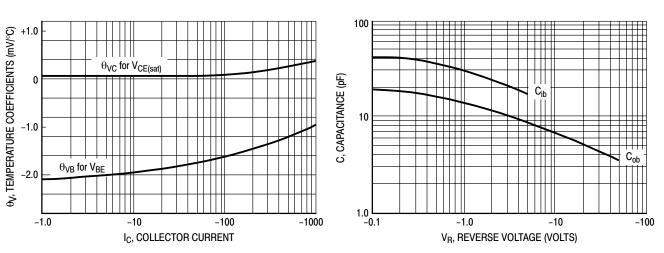


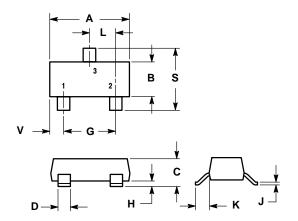
Figure 4. Temperature Coefficients

Figure 5. Capacitances

BC808-25LT1, BC808-40LT1

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-09 **ISSUE AH**



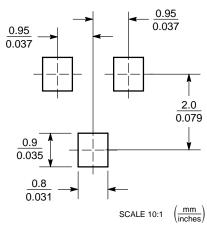
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- MAXIUMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL
- 318-01, -02, AND -06 OBSOLETE, NEW STANDARD 318-09.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.1102	0.1197	2.80	3.04	
В	0.0472	0.0551	1.20	1.40	
С	0.0385	0.0498	0.99	1.26	
D	0.0140	0.0200	0.36	0.50	
G	0.0670	0.0826	1.70	2.10	
Н	0.0040	0.0098	0.10	0.25	
7	0.0034	0.0070	0.085	0.177	
K	0.0180	0.0236	0.45	0.60	
L	0.0350	0.0401	0.89	1.02	
S	0.0830	0.0984	2.10	2.50	
٧	0.0177	0.0236	0.45	0.60	

STYLE 6:

- PIN 1. BASE **EMITTER**
 - COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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